Amendments to the Claims:

This listing of claims will replace the listing of claims, as filed and as amended in the First Preliminary Amendment, in the application:

Listing of Claims:

Claim 1 (original): A method of forming a semiconductor device comprising a semiconductor substrate comprising circuitry and terminal means for establishing electrical connection to the circuitry; providing a sheet for forming a further layer of the device, the sheet comprising at least one groove; applying adhesive to at least one of said substrate and said sheet; and aligning said substrate and said sheet in a position such that said at least one groove faces said terminal means and attaching said substrate and said sheet together by means of said adhesive in said position.

Claim 2 (original): A method according to claim 1, wherein the adhesive is applied solely to said sheet.

Claims 3-15 (canceled).

Claim 16 (original): A semiconductor device assembly comprising a semiconductor substrate comprising circuitry and terminal means for establishing electrical connection to the circuitry; and a sheet attached to the substrate by means of adhesive and forming a further layer of the device, the sheet comprising at least one groove facing and aligned with said terminal means.

Claim 17 (original): A semiconductor device assembly according to claim 16, wherein the terminal means comprise a plurality of bond pads.

Claims 18-32 (canceled).

Claim 33 (new): A method according to claim 1, wherein the terminal means comprises a plurality of bond pads.

Claim 34 (new): A method according to claim 1, wherein the semiconductor substrate comprises at least one array of organic light emitting diodes.

Claim 35 (new): A method according to claim 34, wherein the further layer comprises a translucent layer.

Claim 36 (new): A method according to claim 35, wherein the translucent layer is glass.

Claim 37 (new): A method according to claim 35, wherein the translucent layer bears color filters.

Claim 38 (new): A method according to claim 1, wherein the circuitry comprises a plurality of discrete circuit means each having terminal means at at least one edge thereof, and after attachment of the substrate to the surface said substrate and sheet are singulated by

severing said sheet at the at least one groove to form a plurality of devices each comprising one of said circuit means.

Claim 39 (new): A method according to claim 38, wherein the sheet comprises a plurality of parallel grooves and a further set of parallel grooves intersecting said plurality of parallel grooves at right angles, devices being contained in rectangular portions of the substrate delimited by sections of four intersecting grooves when the sheet and the substrate are attached.

Claim 40 (new): A method according to claim 39, wherein each circuit means has terminal means on all four edges of said rectangular portion.

Claim 41 (new): A method according to claim 38, wherein each circuit means has terminal means on only one edge thereof.

Claim 42 (new): A method according to claim 41, wherein the sheet is severed along lines offset from lines along which the substrate is severed, said lines in said substrate and said lines in said sheet being aligned with said grooves but spaced from each other across the width of said grooves.

Claim 43 (new): A method according to claim 41, wherein the adhesive is applied to parts only of the sheet.

Claim 44 (new): A method according to claim 43, wherein the adhesive is applied to the sheet in lines parallel to the grooves.

Claim 45 (new): A method according to claim 1, wherein the adhesive is applied to the entire surface of the sheet, which surface is to be attached to the substrate.

Claim 46 (new): A semiconductor device assembly according to claim 16, wherein the semiconductor substrate comprises at least one array of organic light emitting diodes.

Claim 47 (new): A semiconductor device assembly according to claim 46, wherein the further layer comprises a translucent layer.

Claim 48 (new): A semiconductor device assembly according to claim 47, wherein the translucent layer is of glass.

Claim 49 (new): A semiconductor device assembly according to claim 47, wherein the translucent layer bears color filters.

Claim 50 (new): A semiconductor device assembly according to claim 16, wherein the circuitry comprises a plurality of discrete circuit means each having terminal means on at least one edge thereof.

Claim 51 (new): A semiconductor device assembly according to claim 50, wherein the sheet comprises a plurality of parallel grooves and a further set of parallel grooves

intersecting said plurality of parallel grooves at right angles, devices being contained in rectangular portions of the substrate delimited by sections of four intersecting grooves when the sheet and the substrate are attached.

Claim 52 (new): A semiconductor device assembly according to claim 51, wherein each circuit means has terminal means on all four edges of said rectangular portion.

Claim 53 (new): A semiconductor device assembly according to claim 50, wherein each circuit means has terminal means on only one edge thereof.

Claim 54 (new): A semiconductor device assembly according to claim 53, wherein the sheet comprises sheet channels for severing the sheet, offset from substrate channels along which the substrate is to be severed, said channels in said substrate and said channels in said sheet being aligned with said grooves but spaced from each other across the width of said grooves.

Claim 55 (new): An optoelectronic device prepared by a process comprising the steps of:

providing a semiconductor substrate comprising circuitry, light emitting elements and terminal means for establishing electrical connection to the circuitry, the circuitry comprising a plurality of discrete circuit means each having terminal means on one edge thereof;

providing a sheet for forming a further layer of the device, the sheet comprising at least one groove;

applying adhesive to at least one of said substrate and said sheet;

aligning said substrate and said sheet in a position such that said at least one groove faces said terminal means; and

attaching said substrate and said sheet together by means of said adhesive in said position;

after attachment of the substrate to the surface, said substrate and sheet are singulated by severing said sheet at the at least one groove to form a plurality of devices each comprising one of said circuit means;

said sheet having a portion extending beyond the substrate, said portion having been formed during the step of severing the sheet along lines offset from lines along which the substrate is severed.

Claim 56 (new): An optoelectronic device according to claim 55, wherein the terminal means comprise a plurality of bond pads.

Claim 57 (new): An optoelectronic device according to claim 56, wherein the semiconductor substrate comprises at least one array of organic light emitting diodes.

Claim 58 (new): An optoelectronic device according to claim 57, wherein the further layer comprises a translucent layer.

Claim 59 (new): An optoelectronic device according to claim 58, wherein the translucent layer is of glass.

Claim 60 (new): An optoelectronic device according to claim 58, wherein the translucent layer bears color filters.